

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	309	257/\$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:30	
2	BRS	L2	146	438/\$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:15	
3	BRS	L3	39	29/\$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:16	
4	BRS	L4	39	361/\$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:17	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	29	174/\$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:17	
6	IS&R	L6	5	((("4908685") or ("6165887") or ("6051450") or ("6165897") or ("20010042781"))).PN.	USPA T; US-P GPUB	2004/07/3 0 19:24	
7	BRS	L11	354	257/\$.ccls. and (die ic chip substrate board carrier) with stitch\$3	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:46	
8	BRS	L12	113	438/\$.ccls. and (die ic chip substrate board carrier) with stitch\$3	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:48	
9	BRS	L13	106	29/\$.ccls. and (die ic chip substrate board carrier) with stitch\$3	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:50	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	L14	44	361/\$.ccls. and (die ic chip substrate board carrier) with stitch\$3	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/07/3 0 19:50	